



Material Composition Declaration

EPC2015C

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	12.5 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	10.5319	84.31	86.49	843147
	Silicon oxide	7631-86-9	0.0404	0.32		3235
	Silicon nitride	12033-89-5	0.0124	0.10		994
	Gallium nitride	25617-97-4	0.0495	0.40		3963
	Aluminum	7429-90-5	0.0839	0.67		6720
	Aluminum nitride	24304-00-5	0.0120	0.10		957
	Titanium	7440-32-6	0.0024	0.02		190
	Titanium nitride	25583-20-4	0.0076	0.06		607
	Copper	7440-50-8	0.0028	0.02		223
	Tungsten	7440-33-7	0.0032	0.03		256
	Polyimide		0.0570	0.46		4566
Under Bump Metal	Titanium	7440-32-6	0.0024	0.02	1.60	189
	Nickel	7440-02-0	0.0702	0.56		5616
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.1270	1.02		10168
Solder Bump	Tin	7440-31-5	1.4513	11.62	11.92	116189
	Silver	7440-22-4	0.0372	0.30		2979
	Copper	7440-50-8	0.0000	0.00		0
Sum in total:			12.5	100.00	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.